

Embedded Die Packaging Technology Market by Platform (Embedded Die in IC Package Substrate, Embedded Die in Rigid Board, Embedded Die in Flexible Board), Industry Vertical (Consumer Electronics, IT and Telecommunication, Automotive, Healthcare, and Others), and Region 2024-2032

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Abstracts

The global embedded die packaging technology market size reached US\$ 92.3 Million in 2023. Looking forward, IMARC Group expects the market to reach US\$ 246.1 Million by 2032, exhibiting a growth rate (CAGR) of 11.17% during 2024-2032.

Embedded die packaging technology is used to embed components inside the substrate via a multi-step manufacturing process. It comprises flip-chip chip scale packaging (FC CSP) and wafer-level chip scale packaging (WL CSP) to improve the efficiency of the system. It creates more space for other components by shrinking overall solutions in the printed circuit board (PCB). It also provides surface-mount technology (SMT) integration and a flexible routing solution to reduce printed circuit board (PCB) size. It offers design flexibility that shifts from 2D to 3D while reducing distortion and power loss. As a result, embedded die packaging technology finds extensive application in electronics, information and technology (IT), automotive, healthcare, and telecommunication industries across the globe.

Embedded Die Packaging Technology Market Trends:

At present, there is an increase in the miniaturization of electronic circuits in microelectronic devices around the world. This, along with the burgeoning semiconductor industry, represents one of the key factors driving the market. Moreover, embedded die packaging technology offers several benefits, such as upgraded

electrical and thermal performance, heterogeneous integration, and streamlined logistics for original equipment manufacturers (OEMs), which are contributing to the growth of the market. In addition, the increasing adoption of autonomous robots for professional services in various industries is offering lucrative growth opportunities to industry investors. Besides this, the growing utilization of embedded die packaging technology in smartphones and wearable devices to enhance the available space and integrate more components is positively influencing the market. Additionally, there is a rise in the demand for embedded die packaging technology with integrated internet of things (IoT) across the globe. This, coupled with the increasing sales of portable electronic devices, such as laptops, computers, tablets, e-readers, smartphones, MP3 players, drones, and electronic toys, is bolstering the growth of the market.

Key Market Segmentation:

IMARC Group provides an analysis of the key trends in each sub-segment of the global embedded die packaging technology market report, along with forecasts at the global, regional and country level from 2024-2032. Our report has categorized the market based on platform and industry vertical.

Breakup by Platform:

Embedded Die in IC Package Substrate

Embedded Die in Rigid Board

Embedded Die in Flexible Board

Breakup by Industry Vertical:

Consumer Electronics

IT and Telecommunication

Automotive

Healthcare

Others

Breakup by Region:

North America

United States

Canada

Asia-Pacific

China

Japan
India
South Korea
Australia
Indonesia
Others
Europe
Germany
France
United Kingdom
Italy
Spain
Russia
Others
Latin America
Brazil
Mexico
Others
Middle East and Africa

Competitive Landscape:

The competitive landscape of the industry has also been examined along with the profiles of the key players being Amkor Technology Inc., ASE Technology Holding Co. Ltd., AT & S Austria Technologie & Systemtechnik Aktiengesellschaft, Fujikura Ltd., Infineon Technologies AG, Microsemi Corporation (Microchip Technology Inc.), Schweizer Electronic AG and TDK Electronics AG (TDK Corporation). Kindly, note that this only represents a partial list of companies, and the complete list has been provided in the report.

Key Questions Answered in This Report

1. What was the size of the global embedded die packaging technology market in 2023?
2. What is the expected growth rate of the global embedded die packaging technology market during 2024-2032?
3. What are the key factors driving the global embedded die packaging technology market?
4. What has been the impact of COVID-19 on the global embedded die packaging technology market?
5. What is the breakup of the global embedded die packaging technology market based

on the platform?

6. What is the breakup of the global embedded die packaging technology market based on the industry vertical?

7. What are the key regions in the global embedded die packaging technology market?

8. Who are the key players/companies in the global embedded die packaging technology market?

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